

Title (en)

METAL POWDER FOR POWDER METALLURGY, COMPOUND, GRANULATED POWDER, AND SINTERED BODY

Title (de)

METALLPULVER FÜR PULVERMETALLURGIE, VERBINDUNG, GRANULIERTES PULVER UND GESINTERTER KÖRPER

Title (fr)

POUDRE DE MÉTAL POUR MÉTALLURGIE DES POUDRES, COMPOSÉ, POUDRE GRANULÉE ET CORPS FRITTÉ

Publication

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Application

EP 16150037 A 20160104

Priority

JP 2015000678 A 20150106

Abstract (en)

[origin: EP3042974A2] A metal powder for powder metallurgy according to the invention contains Fe as a principal component, Cr in a proportion of 15 mass% or more and 26 mass% or less, Ni in a proportion of 7 mass% or more and 22 mass% or less, Si in a proportion of 0.3 mass% or more and 1.2 mass% or less, and C in a proportion of 0.005 mass% or more and 0.3 mass% or less, wherein when two elements selected from the group consisting of Ti, V, Y, Zr, Nb, Hf, and Ta are defined as a first element and a second element, the first element is contained in a proportion of 0.01 mass% or more and 0.5 mass% or less and the second element is contained in a proportion of 0.01 mass% or more and 0.5 mass% or less. Further, the metal powder for powder metallurgy preferably has an austenite crystal structure.

IPC 8 full level

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